

Contents

About the Editors XIX

Series Editor Preface XXI

Volume Editors Preface XXIII

List of Contributors XXVII

Part I Physical and Mathematical Fundamentals 1

- 1 **Introduction: Issues in Microsystems Modeling 3**
Gary K. Fedder and Tamal Mukherjee
 - 1.1 The Need for System-Level Models for Microsystems 3
 - 1.2 Coupled Multiphysics Microsystems 4
 - 1.3 Multiscale Modeling and Simulation 6
 - 1.4 System-Level Model Terminology 7
 - 1.5 Automated Model Order Reduction Methods 9
 - 1.6 Handling Complexity: Following the VLSI Paradigm 10
 - 1.7 Analog Hardware Description Languages 11
 - 1.8 General Attributes of System-Level Models 12
 - 1.9 AHDL Simulation Capabilities 13
 - 1.10 Composable Model Libraries 14
 - 1.11 Parameter Extraction, Model Verification, and Model Validation 15
 - 1.12 Conclusions 16
 - References 17
- 2 **System-Level Modeling of MEMS Using Generalized Kirchhoffian Networks – Basic Principles 19**
Gabriele Schrag and Gerhard Wachutka
 - 2.1 Introduction and Motivation 19
 - 2.2 Generalized Kirchhoffian Networks for the Tailored System-Level Modeling of Microsystems 20

2.2.1	Generic Modeling Approach for Microdevices and Systems	21
2.2.2	From Continuous-Field Level to Compact Models	23
2.2.3	Approaches to Compact Model Derivation	29
2.2.3.1	Finite Network (FN) Models	29
2.2.3.2	Compact Modeling of MEMS	30
2.2.3.3	Mixed-Level Modeling (MLM)	31
2.2.3.4	Mathematical Model Order Reduction (MOR)	32
2.3	Application 1: Physics-Based Electrofluidic Compact Model of an Electrostatically Actuated Micropump	32
2.3.1	Compact Model of the Membrane Drive	34
2.3.2	Compact Model of the Valves	36
2.3.3	System-Level Model of the Tubes	38
2.3.4	Physics-Based System-Level Model of the Micropump	39
2.3.5	Model Calibration and Parameter Extraction	40
2.4	Application 2: Electrostatically Actuated RF MEMS Switch	41
2.4.1	Conclusions	46
	References	48
3	System-Level Modeling of MEMS by Means of Model Order Reduction (Mathematical Approximations) – Mathematical Background	53
	<i>Lihong Feng, Peter Benner, and Jan G. Korvink</i>	
3.1	Introduction	53
3.2	Brief Overview	55
3.3	Mathematical Preliminaries	56
3.3.1	Scalar, Vector, and Matrix	57
3.3.2	Vector Space, Subspace, Linear Independence, and Basis	57
3.3.3	Laplace Transform	60
3.3.4	Rational Function	60
3.3.5	Norms	61
3.3.5.1	Vector and Matrix Norms	61
3.3.5.2	Vector Function Norms and Matrix Function Norms	62
3.4	Numerical Algorithms	63
3.5	Linear System Theory	66
3.5.1	Transfer Function	66
3.5.2	Measure of the Difference between Any Two Different LTI Systems	67
3.5.3	Controllability and Observability	68
3.5.4	Realization Theory	69
3.5.5	Stability and Passivity of a System	70
3.6	Basic Idea of Model Order Reduction	71
3.7	Moment-Matching Model Order Reduction	73
3.7.1	Moments and Moment Vectors	73
3.7.2	Computation of the Projection Matrices W and V	74
3.7.3	Different Choices of the Expansion Points	75
3.7.4	Development of Moment-Matching MOR	76

3.8	Gramian-Based Model Order Reduction	77
3.8.1	Motivation of Balanced Truncation	78
3.8.2	Balancing Transformation	78
3.8.3	Truncation	80
3.8.4	Computation of the Balancing Transformation	81
3.8.5	Acceleration Methods of Computing the Gramians	82
3.8.6	Extension to More General Systems	83
3.9	Stability, Passivity, and Error Estimation of the Reduced Model	84
3.9.1	Stability, Passivity, and Error Bound of Moment-Matching MOR	84
3.9.2	Stability, Passivity, and Error Bound of the Gramian-Based MOR	84
3.10	Dealing with Nonzero Initial Condition	85
3.11	MOR for Second-Order, Nonlinear, Parametric systems	86
3.12	Conclusion and Outlook	86
	References	87
4	Algorithmic Approaches for System-Level Simulation of MEMS and Aspects of Cosimulation	95
	<i>Peter Schneider, Christoph Clauß, Ulrich Donath, Günter Elst, Olaf Enge-Rosenblatt, and Thomas Uhle</i>	
4.1	Introduction	95
4.2	Mathematical Structure of MEMS Models	96
4.2.1	Differential and Algebraic Equations	97
4.2.1.1	Multibody Systems	98
4.2.1.2	Fluidic Systems	99
4.2.1.3	Networks	101
4.2.2	Boolean Equations and Finite State Machines	102
4.3	General Approaches for System-Level Model Description	104
4.3.1	SPICE and Macromodeling	104
4.3.2	Model Description Languages	105
4.4	Numerical Methods for System-Level Simulation	107
4.4.1	Solution of Nonlinear DAEs	107
4.4.2	Mixed-Signal Simulation Cycle	109
4.4.3	Cosimulation	110
4.4.3.1	Coupling Algorithms	111
4.4.3.2	Cosimulation Interface	112
4.5	Emerging Problems and Advanced Simulation Techniques	113
4.5.1	Discontinuous Forcing Functions	114
4.5.2	Structural Changes in Model Equations	117
4.6	Conclusion	118
	References	118

Part II Lumped Element Modeling Method for MEMS Devices 123

5	System-Level Modeling of Surface Micromachined Beamlike Electrothermal Microactuators 125
	<i>Ren-Gang Li and Qing-An Huang</i>
5.1	Introduction 125
5.2	Classification and Problem Description 127
5.2.1	In-Plane 127
5.2.1.1	U-Shaped Actuator 127
5.2.1.2	Bent-Beam Actuators 128
5.2.1.3	Long-Short Beam Actuator 128
5.2.2	Out of Plane 129
5.2.3	Material Properties 129
5.2.3.1	Thermal Conductivity 129
5.2.3.2	Specific Heat 130
5.2.3.3	Resistivity 130
5.2.3.4	Coefficient of Thermal Expansion 130
5.3	Modeling 131
5.3.1	Electrothermal Model of a Beam 131
5.3.2	Thermomechanical Model of the Beam 134
5.4	Solving 136
5.4.1	Equivalent Circuit of a Coupled Electrothermal Model 137
5.4.2	Equivalent Circuit of the Thermomechanical Model of a Beam 138
5.5	Case Study 139
5.6	Conclusion and Outlook 142
	References 143
6	System-Level Modeling of Packaging Effects of MEMS Devices 147
	<i>Jing Song and Qing-An Huang</i>
6.1	Introduction 147
6.2	Packaging Effects of MEMS and Their Impact on Typical MEMS Devices 148
6.2.1	Accelerometers 148
6.2.2	Gyros 149
6.2.3	Pressure Sensors 149
6.2.4	Thermal Actuators 149
6.2.5	Hall Sensors 150
6.3	System-Level Modeling 150
6.3.1	System Partitioning 151
6.3.2	Behavioral Modeling of Single Substructures 152
6.3.2.1	Microbeam Model 152
6.3.2.2	Chip/Adhesive/Package Model 153
6.3.2.3	Support Model 155
6.3.3	Element Integration 156
6.3.4	FEM and Experimental Validation 157

6.4	Conclusion and Outlook	160
	References	160
7	Mixed-Level Approach for the Modeling of Distributed Effects in Microsystems	163
	<i>Martin Niessner and Gabriele Schrag</i>	
7.1	General Concept of Finite Networks and Mixed-Level Models	163
7.2	Approaches for the Modeling of Squeeze Film Damping in MEMS	165
7.2.1	Reynolds Equation-Based Modeling Strategies	166
7.2.2	Motivation for Using Mixed-Level Modeling	168
7.3	Mixed-Level Modeling of Squeeze Film Damping in MEMS	169
7.3.1	Finite Network-Based Evaluation of the Reynolds Equation	170
7.3.2	Physics-Based Lumped Element Models	173
7.3.2.1	Boundary Model	173
7.3.2.2	Hole Model	174
7.3.3	Gas Rarefaction Effects	175
7.3.4	Calculation of the Total Damping Force	177
7.3.5	Coupling with Mechanical Models	177
7.3.6	Automated Model Generation	178
7.4	Evaluation	179
7.4.1	Numerical Evaluation	179
7.4.2	Experimental Evaluation	180
7.4.3	Comparison with Alternative Damping Models	185
7.5	Conclusion	186
	References	187
8	Compact Modeling of RF-MEMS Devices	191
	<i>Jacopo Iannacci</i>	
8.1	Introduction	191
8.2	Brief Description of the MEMS Compact Modeling Approach	192
8.3	RF-MEMS Multistate Attenuator Parallel Section	194
8.4	RF-MEMS Multistate Attenuator Series Section	202
8.5	Whole RF-MEMS Multistate Attenuator Network	205
8.6	Conclusions	207
	References	208
	Part III Mathematical Model Order Reduction for MEMS Devices	211
9	Moment-Matching-Based Linear Model Order Reduction for Nonparametric and Parametric Electrothermal MEMS Models	213
	<i>Tamara Bechtold, Dennis Hohlfeld, Evgenii B. Rudnyi, and Jan G. Korvink</i>	
9.1	Introduction	213
9.2	Methodology for Applying Model Order Reduction to Electrothermal MEMS Models: Review of Achieved Results and Open Issues	213
9.3	MEMS Case Study – Silicon-Based Microhotplate	220

9.4	Application of the Reduced-Order Model for the Parameterization of the Controller	223
9.5	Application of Parametric Reduced-Order Model to the Extraction of Thin-Film Thermal Parameters	227
9.5.1	Parametric Model Order Reduction	228
9.5.2	Parameter Extraction Methodology	230
9.6	Conclusion and Outlook	232
	References	234
10	Projection-Based Nonlinear Model Order Reduction	237
	<i>Amit Hochman, Dmitry M. Vasilyev, Michał J. Rewieński, and Jacob K. White</i>	
10.1	Introduction	237
10.2	Problem Specification	238
10.3	Projection Principle and Evaluation Cost for Nonlinear Systems	239
10.4	Taylor Series Expansions	240
10.4.1	Microfluidic Channel Example	241
10.4.2	Model Reduction via Quadratic Taylor Expansion	242
10.4.3	Stability Issues	244
10.4.4	Taylor Series Expansions: Summary	245
10.5	Trajectory Piecewise-Linear Method	245
10.5.1	Nonlinear Transmission-line Model	246
10.5.2	Stability Issues	247
10.5.3	TPWL Summary	249
10.6	Discrete Empirical Interpolation method	250
10.6.1	Thermal Analysis	251
10.6.2	Stability Issues	253
10.6.3	DEIM Summary	254
10.7	A Comparative Case Study of an MEMS Switch	255
10.7.1	Pull-In Effect	256
10.7.2	Generalizing from Training Inputs	258
10.7.3	Harmonic Distortion	258
10.7.4	A Note about CPU Times	259
10.8	Summary and Outlook	260
	Acknowledgment	260
	References	261
11	Linear and Nonlinear Model Order Reduction for MEMS Electrostatic Actuators	263
	<i>Jan Lienemann, Emanuele Bertarelli, Andreas Greiner, and Jan G. Korvink</i>	
11.1	Introduction	263
11.2	The Variable Gap Parallel Plate Capacitor	264
11.2.1	Pull-In	266
11.2.2	Regimes of the Trajectory	268
11.3	Model Order Reduction Methods	269

11.3.1	Representation of Nonlinearities	270
11.3.2	MOR Methods for Second-Order Linear Systems	270
11.3.3	MOR Methods for Nonlinear Systems	272
11.3.3.1	Polynomial Projection	273
11.3.3.2	Trajectory Piecewise-Linear (TPWL) Method	274
11.4	Example 1: IBM Scanning-Probe Data Storage Device	275
11.4.1	Cantilever Model	277
11.4.2	Model Order Reduction with Polynomial Projection	277
11.4.2.1	Extraction of Nonlinear System	277
11.4.2.2	Polynomial Approximation	278
11.4.2.3	Model Order Reduction of the Polynomial System	278
11.4.3	Results	279
11.4.4	Discussion	281
11.5	Example 2: Electrostatic Micropump Diaphragm	281
11.5.1	Plate Model Formulation	282
11.5.2	Model Order Reduction by TPWL and Arnoldi Methods	284
11.6	Results and Discussion	285
11.7	Conclusions	286
	Acknowledgments	287
	References	287
12	Modal-Superposition-Based Nonlinear Model Order Reduction for MEMS Gyroscopes	291
	<i>Jan Mehner</i>	
12.1	Introduction	291
12.2	Model Order Reduction via Modal Superposition	292
12.3	MEMS Testcase: Vibratory Gyroscope	293
12.4	Flow Chart of the Nonlinear Model Order Reduction Procedure	294
12.5	Theoretical Background of Modal Superposition Technologies	295
12.5.1	Linear Mechanical Systems	295
12.5.2	Nonlinear Electromechanical Interactions and Body Loads of Capacitive Sensors	297
12.5.3	Parametric Reduced Order Models for Packaging Interactions	298
12.6	Specific Algorithms of the Reduced Order Model Generation Pass	299
12.6.1	Extraction of Body Load Contribution Vectors for Modal Superposition	299
12.6.2	Extraction of Capacitances for Comb Cell Conductors and Platelike Capacitors	301
12.6.3	Data Sampling and Function Fit Procedures for Multivariable Capacitances	302
12.7	System Simulations of MEMS Based on Modal Superposition	304
12.7.1	Behavioral Analysis of Vibratory Gyroscopes in Matlab/Simulink	304

- 12.7.2 Simulations with Reduced Order Models Based on Kirchhoffian Networks 306
- 12.7.3 Expansion of System Simulation Results to Full Order FEM Models 306
- 12.8 Conclusion and Outlook 307
- References 308

Part IV Modeling of Entire Microsystems 311

- 13 Towards System-Level Simulation of Energy Harvesting Modules 313**
Dennis Hohlfeld, Tamara Bechtold, Evgenii B. Rudnyi, Bert Op het Veld, and Rob van Schaijk
 - 13.1 Introduction 313
 - 13.1.1 Wireless Autonomous Sensor Nodes 314
 - 13.1.2 Micropower Module 315
 - 13.1.3 Vibrational Harvesters 316
 - 13.2 Design and Fabrication of the Piezoelectric Generator 317
 - 13.3 Experimental Results 318
 - 13.4 Modeling and Simulation 318
 - 13.4.1 Lumped Element Modeling 319
 - 13.4.2 Finite Element Modeling 320
 - 13.4.3 Model Order Reduction 322
 - 13.4.4 Transient MEMS Circuit Cosimulation 323
 - 13.4.5 Harmonic MEMS Circuit Cosimulation 325
 - 13.5 Maximum Power Point for the Piezoelectric Harvester 327
 - 13.5.1 Complex Matching 328
 - 13.5.2 Real Matching 330
 - 13.5.3 Consequence of Matching 331
 - 13.6 Conclusions and Outlook 332
 - References 333
- 14 Application of Reduced Order Models in Circuit-Level Design for RF MEMS Devices 335**
Laura Del Tin, Evgenii B. Rudnyi, and Jan G. Korvink
 - 14.1 Model Equations for RF MEMS Devices 337
 - 14.2 Extraction of the Reduced Order Model 340
 - 14.2.1 Second Order ODE Systems 341
 - 14.2.2 Handling Nonlinearities in the Input Function 341
 - 14.2.3 Extraction Procedure 343
 - 14.3 Application Examples 345
 - 14.3.1 Vibrating Devices 345
 - 14.3.2 Microswitch 351
 - 14.4 Conclusion and Outlook 354
 - References 355

15	SystemC AMS and Cosimulation Aspects	357
	<i>François Pêcheux, Marie-Minerve Louërat, and Karsten Einwich</i>	
15.1	Introduction	357
15.2	Heterogeneous Modeling with SystemC AMS	358
15.2.1	SystemC AMS Timed Dataflow (TDF)	358
15.2.2	Timed Dataflow Model of the Accelerometer	359
15.2.3	Electrical Linear Network Model of the MEMS Accelerometer	361
15.3	Case Study: Detection of Seismic Perturbations Using the Accelerometer	363
15.3.1	Seismic Stimuli and Seismic Sensors in SystemC AMS TDF	365
15.3.2	Digital Controller in SystemC	365
15.3.3	2.4 GHz RF Transceiver	366
15.3.4	Battery Modeling	368
15.3.5	Embedded Software, Cross-Compiled GNU GCC Application for MIPS	369
15.3.6	Simulation Results	369
15.4	Conclusion	370
	Appendix	371
	References	374
16	System Level Modeling of Electromechanical Sigma–Delta Modulators for Inertial MEMS Sensors	377
	<i>Michael Kraft</i>	
16.1	Introduction and Motivation	377
16.2	Second Order Electromechanical $\Sigma\Delta$ for a MEMS Accelerometer	380
16.2.1	Basic Model	380
16.2.2	Advanced Model	386
16.3	Higher Order Electromechanical $\Sigma\Delta$ for MEMS Accelerometer	391
16.3.1	Design Methodology for Higher Order EM $\Sigma\Delta$	391
16.3.2	Example Design	392
16.3.3	Feedback Linearization	395
16.3.4	Advanced Model	396
16.4	Higher Order Electromechanical $\Sigma\Delta$ for MEMS Gyroscopes	397
16.5	Concluding Remarks	400
	References	401
	Part V Software Implementations	405
17	3D Parametric-Library-Based MEMS/IC Design	407
	<i>Gunar Lorenz and Gerold Schröpfer</i>	
17.1	About Schematic-Driven MEMS Modeling	407
17.2	A 3D Parametric Library for MEMS Design—MEMS+ [®]	409
17.2.1	3D Design Entry for MEMS	409

17.2.2	MEMS Model Library	410
17.2.3	Integration with System Simulators	412
17.2.4	Integration with MATLAB and Simulink	413
17.2.5	Integration with EDA Tools	414
17.3	Toward Manufacturable MEMS Designs	415
17.3.1	Parameterization of Process and Material Properties	415
17.3.2	Process Design Kits	418
17.4	Micromirror Array Design Example	419
17.5	Conclusions	422
	References	423
18	MOR for ANSYS	425
	<i>Evgenii B. Rudnyi</i>	
18.1	Introduction	425
18.2	Practice-Oriented Research during the Development of MOR for ANSYS	426
18.3	Programming Issues	429
18.3.1	Obtaining System Matrices from ANSYS	430
18.3.2	Solvers	431
18.4	Open Problems	432
18.5	Conclusion	436
	References	437
19	SUGAR: A SPICE for MEMS	439
	<i>Jason V. Clark</i>	
19.1	Introduction	439
19.2	SUGAR	439
19.2.1	Equation of Motion	440
19.3	SUGAR-Based Applications	444
19.3.1	Library	444
19.3.2	Design/Simulation	445
19.3.3	Layout Generation	445
19.3.4	Common Ground Tracers	445
19.3.5	Etch Holes	447
19.3.6	Multilayer Pads	447
19.3.7	Parameterized Arrays	447
19.3.8	Optimization	448
19.3.9	NEMS	448
19.3.10	PSugar	450
19.3.11	GUI Configuration	450
19.3.12	DAEs	451
19.3.13	Simulation	453
19.4	Integration of SUGAR + COMSOL + SPICE + SIMULINK	454
19.4.1	Integration	456
19.4.2	Verification	457

19.5	Conclusion	457
	References	458
20	Model Order Reduction Implementations in Commercial MEMS Design Environment	461
	<i>Sandeep Akkaraju</i>	
20.1	Introduction	461
20.1.1	<i>Ab initio</i> (First Principles) Simulations	461
20.1.2	Technology CAD (TCAD)	462
20.1.3	Schematic or Component-Based Design (Top-Down Design)	462
20.1.4	Layout-Based Design (Bottom-Up Design)	463
20.1.5	System Model Extraction (SME)	464
20.1.6	Verification	465
20.1.7	System Simulation	467
20.2	IntelliSense's Design Methodology	467
20.2.1	From the Top Down	467
20.2.2	One Step at a Time	468
20.2.3	Closing the Loop	469
20.3	Implementation of System Model Extraction in IntelliSuite	470
20.3.1	High-Level Overview	470
20.3.2	Capturing Residual Stress and Film Damping Effects	471
20.3.3	Implementation	473
20.4	Benchmarks	474
20.4.1	Accelerometer	474
20.4.2	Inertial Gyroscope	474
20.4.3	Fluid Damping	477
20.4.4	Coupled Package-Device Modeling	478
20.5	Summary	480
	References	481
21	Reduced Order Modeling of MEMS and IC Systems – A Practical Approach	483
	<i>Sebastien Cases and Mary-Ann Maher</i>	
21.1	Introduction	483
21.2	The MEMS Development Environment	484
21.3	Modeling Requirements and Implementation within SoftMEMS Simulation Environment	485
21.3.1	Models and Inputs	487
21.3.2	Modeling Process	490
21.3.3	Model Output	492
21.3.4	Parameterization	492
21.4	Applications	494
21.5	Conclusions and Outlook	498
	References	498

22	A Web-Based Community for Modeling and Design of MEMS	501
	<i>Peter J. Gilgunn, Jason V. Clark, Narayan Aluru, Tamal Mukherjee, and Gary K. Fedder</i>	
22.1	Introduction	501
22.2	The MEMS Modeling and Design Landscape	501
22.3	Leveraging Web-Based Communities	502
22.3.1	Concepts of Web-Based Design	503
22.3.2	Design Community Constitution	504
22.4	MEMS Modeling and Design Online	505
22.4.1	System-Level Modeling of MEMS	506
22.4.2	Web-Based Community Conventions	507
22.5	Encoding MEMS Behavioral Models	508
22.5.1	Inside the Black Box – Nonlinear Beam	509
22.5.2	Behavioral Model Performance – Nonlinear Beam	511
22.5.3	Behavioral Model Extensions	512
22.5.4	Behavioral Model Composability	513
22.6	Conclusions and Outlook	515
	References	515
	Index	519